FEB 072006

orrespondence is being deposited with the U.S. Postal in postage as First Class Mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date shown below.

Dated: February 3, 2006

Docket No.: 28569/38510

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Mingming Fang et al.

Application No.: 10/677,433

Filed: October 2, 2003

For: CHEMICAL-MECHANICAL POLISHING

(CMP) SLURRY AND METHOD OF

PLANARIZING SURFACES

Confirmation No.: 9007

Art Unit: 1765

Examiner: P. A. George

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated November 15, 2005, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.